## CLAIM AMENDMENTS

Claim 1 (Currently Amended)

A circuit board comprising a base material, a conductive pattern which is formed on the base material, and a resin layer which comprises a photocurable resin, the resin layer being ~~is~~ formed on the conductive pattern by curing the ~~a~~ photocurable resin,

wherein a line width of the conductive pattern is 20 μm or less.

Claim 2 (Original)

The circuit board of claim 1, wherein the photocurable resin comprises a photo polymerization initiator and a photocurable acrylic type monomer or a photocurable acrylic type oligomer as main components.

Claim 3 (Cancelled)

Claim 4 (Original)

The circuit board of claim 1, further comprising a magnetic shielding layer provided at least one of between the base material and the conductive pattern, and on a surface plane where the conductive pattern is not formed in the base material.

Claim 5 (Withdrawn)

A manufacturing method of a circuit board, comprising;

drawing a droplet pattern with droplets of a conductive pattern forming composition on a surface of a base material,

heating the drawn droplet pattern so as to convert the droplet pattern into a conductive pattern,

coating a photocurable resin onto the conductive pattern after the heating, and

irradiating light to cure the coated photocurable resin after the coating.

Claim 6 (Withdrawn)

The method of claim 5, wherein the drawing comprises drawing the droplet pattern by jetting droplets of the conductive pattern forming composition in an ink-jet method.

Claim 7 (Withdrawn)

The method of claim 5, wherein the drawing comprises jetting the conductive pattern forming composition from a nozzle having a nozzle diameter of 0.1 μm to 10 μm.

Claim 8 (Withdrawn)

The method of claim 5, wherein the drawing comprises drawing the droplet pattern having line width of 20 μm or less.

Claim 9 (Withdrawn)

The method of claim 5, wherein the conductive pattern forming composition comprises conductive fine particles having at least one kind of metal, and a dispersant which disperses the conductive pattern fine particles, and

wherein the dispersant comprises a polymer in which a main chain of the polymer comprises tertiary amine type monomer and a side chain of the polymer comprises polyether type anionic monomer.

Claim 10 (Withdrawn)

The method of claim 5, wherein a sol-gel solution for forming a magnetic shielding layer is coated onto at least one surface of the base material and is cured to be the magnetic shielding layer, and subsequently the drawing is performed onto at least one of a surface of the magnetic shielding layer and a surface of the base material.

Claim 11 (Withdrawn)

The method of claim 5, wherein a sol-gel solution for forming a magnetic shielding layer is coated onto a reverse side of a surface where the conductive pattern is formed by the heating in the base material, and is cured to form the magnetic shielding layer.

Claim 12 (New)

The circuit board of claim 1, wherein the conductive pattern comprises conductive fine particles made of at least one kind of metal and a dispersant whose main chain comprises a tertiary amine type monomer.

Claim 13 (New)

The circuit board of claim 12, wherein weight average molecular weight of the dispersant is 3,000 to 100,000.

Claim 14 (New)

The circuit board of claim 12, wherein the main chain of the dispersant further comprises (meth)acrylic acid or a derivative thereof.